What is claimed is:

1. A photoresist composition comprising a polymeric binder, a photoactive component, an organic acid and optionally a cross-linking agent, wherein the organic acid is non-polymerizable with the polymeric binder, optional cross-linking agent or both.

2. The composition of claim 1 wherein the organic acid is selected from carboxylic acids or sulfonic acids.

3. The composition of claim 2 wherein the organic acid is selected from alkanecarboxylic acids, arylcarboxylic acids, alkanesulfonic acids or arylsulfonic acids.

4. The composition of claim 3 wherein the organic acid is selected from (C_1-C_{12})alkylcarboxylic acids, (C_1-C_{12})alkyldicarboxylic acids, (C_1-C_{12})alkyltricarboxylic acids, substituted (C_1-C_{12})alkylcarboxylic acids, substituted (C_1-C_{12})alkyldicarboxylic acids, substituted (C_1-C_{12})alkyltricarboxylic acids, amine carboxylic acids, aryldicarboxylic acids or substituted arylcarboxylic acids.

5. The composition of claim 4 wherein the organic acid is selected from formic acid, acetic acid, propionic acid, oxalic acid, malonic acid, succinic acid, glutaric acid, adipic acid, glycolic acid, lactic acid, tartaric acid, citric acid or malic acid, ethylenediamine tetraacetic acid, phthalic acid, benzene tricarboxylic acid, salicilic acid, cyclohexanecarboxylic acid, 1,4-cyclohexanedicarboxylic acid or sebacic acid.

6. The composition of claim 1 wherein the photoresist is negative-acting.

7. The composition of claim 1 wherein the photoactive component is selected from 9-phenylacridine, n-phenylglycine, benzophenone, N, N'-tetramethyl-4, 4'-diaminobenzophenone, N,N'-tetraethyl-4,4'-diaminobenzophenone, 4-methoxy-4'-dimethylaminobenzophenone, 3,3'-dimethyl-4-methoxybenzophenone, p,p'-bis(dimethylamino)benzophenone, p,p'-bis(diethylamino)-benzophenone, anthraquinone, 2-ethylanthraquinone, naphthaquinone, phenanthraquinone, benzoin, benzoinmethylether, benzoinethylether, benzoinisopropylether, benzoin-n-butylether, benzoin-phenylether, methylbenzoin, ethybenzoin, dibenzyl, benzyldiphenyldisulfide, benzyldimethylketal, 1,7-bis(9-acridinyl)heptane, 2-chlorothioxanthone, 2-methylthioxanthone, 2,4-diethylthioxanthone, 2,4-dimethylthioxanthone, 2-isopropylthioxanthone, 1,1-dichloroacetophenone, p-t-butyldichloro-acetophenone, 2,2-diethoxyacetophenone, 2,2-dimethoxy-2-phenylacetophenone, 2,2-dichloro-4-

phenoxyacetophenone, 2-(o-chlorophenyl)-4,5-diphenylimidazole dimer, 2-(o-chlorophenyl)-4,5-di(m-methoxyphenyl imidazole dimer, 2-(o-fluorophenyl)-4,5-diphenylimidazole dimer, 2-(o-methoxyphenyl)-4,5-diphenylimidazole dimer, 2-(p-methoxyphenyl)-4,5-diphenylimidazole dimer, 2,4-di(p-methoxyphenyl)-5-phenylimidazole dimer, 2-(2,4-dimethoxyphenyl)-4,5-diphenylimidazole dimer or 2-(p-methylmercaptophenyl)-4,5-diphenylimidazole dimer.

8. The composition of claim 1 wherein the polymeric binder comprises sufficient acid functionality to render said photoimageable composition developable in alkaline aqueous solution.

9. The composition of claim 8 wherein the polymeric binder has an acid number of from about 50 to about 250.

10. The composition of claim 1 wherein the organic acid is present in an amount up to 10 %wt.

11. The composition of claim 10 wherein the organic acid is present in an amount up to 8 %wt.

12. A method of enhancing the removal of a photoresist composition from a substrate comprising the step of combining an organic acid with a photoresist composition comprising polymeric binder, a photoactive component and optionally a cross-linking agent, wherein the organic acid is non-polymerizable with the polymeric binder, optional cross-linking agent or both.

13. The method of claim 12 wherein the organic acid is selected from carboxylic acids or sulfonic acids.

14. The method of claim 13 wherein the organic acid is selected from alkanecarboxylic acids, arylcarboxylic acids, alkanesulfonic acids or arylsulfonic acids.

15. The method of claim 14 wherein the organic acid is selected from (C_1-C_{12})alkylcarboxylic acids, (C_1-C_{12})alkyldicarboxylic acids, (C_1-C_{12})alkyltricarboxylic acids, substituted (C_1-C_{12})alkylcarboxylic acids, substituted (C_1-C_{12})alkyldicarboxylic acids, substituted (C_1-C_{12})alkyltricarboxylic acids, amine carboxylic acids, aryldicarboxylic acids or substituted arylcarboxylic acids.

16. The method of claim 15 wherein the organic acid is selected from formic acid, acetic acid, propionic acid, oxalic acid, malonic acid, succinic acid, glutaric acid, adipic acid, glycolic acid, lactic acid, tartaric acid, citric acid or malic acid, ethylenediamine tetraacetic acid, phthalic acid, benzene tricarboxylic acid, salicilic acid, cyclohexanecarboxylic acid, 1,4-cyclohexanedicarboxylic acid or sebacic acid.

17. The method of claim 12 wherein the photoresist is negative-acting.

18. A method of manufacturing a printed wiring board comprising the steps of: a) disposing on a printed wiring board substrate a photoresist composition comprising a polymeric binder, a photoactive component, an organic acid and optionally a cross-linking agent, wherein the organic acid is non-polymerizable with the polymeric binder and optional cross-linking agent; b) imaging the photoresist; and c) developing the photoresist.

19. The method of claim 18 wherein the organic acid is selected from alkanecarboxylic acids, arylcarboxylic acids, alkanesulfonic acids or arylsulfonic acids.

20. The method of claim 19 wherein the organic acid is selected from from (C_1-C_{12})alkylcarboxylic acids, (C_1-C_{12})alkyldicarboxylic acids, (C_1-C_{12})alkyltricarboxylic acids, substituted (C_1-C_{12})alkylcarboxylic acids, substituted (C_1-C_{12})alkyldicarboxylic acids, substituted (C_1-C_{12})alkyltricarboxylic acids, amine carboxylic acids, aryldicarboxylic acids or substituted arylcarboxylic acids.